* In Examiners Reference

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1 – 43: Cancelled

44. (New) An apparatus for treating disc-shaped substrates, comprising:

a device (10) for rotating said substrates (3) about an axis of rotation A; and

at least one first group of nozzles, (40, 60, 80) wherein the nozzles of said first group are differently spaced relative to said axis of rotation A, and wherein said nozzles are adapted to be controlled individually or in sub groups.

45. (New) An apparatus according to claim 44, which comprises at least one further group of nozzles (44, 48; 62; 82) wherein the nozzles of said second group are differently spaced relative to said axis of rotation A.

46. (New) An apparatus according to claim 45, wherein said nozzles of said second group are adapted to be controlled individually or in sub groups.

47. (New) An apparatus according to claim 45, wherein three groups of nozzles (40, 44, 48) are provided.

48. (New) An apparatus according to claim 45, wherein nozzles of at least one further group of nozzles (44, 48; 62; 82) are, with regard to their spacing relative to said axis of rotation A, offset relative to said nozzles of said at least one first group of nozzles (40, 60, 80.)

49. (New) An apparatus according to claim 45, wherein nozzles ofat least one group of nozzles (40, 44, 48; 60, 62; 80) are disposed along a straight line that extends radially relative to said axis of rotation A.

50. (New) An apparatus according to claim 49, wherein said nozzles of at least two

groups of nozzles 44, 48; 60, 62; 80, 82 are disposed along a common straight line.

51. (New) An apparatus according to claim 50, wherein said nozzles of one group of nozzles 44, 48; 60, 62; 80, 82 are disposed between said nozzles of another group of nozzles 48, 44; 62, 60; 82, 80.

52. (New) An apparatus according to claim 45, wherein said nozzles of at least one group of nozzles 40, 44, 48; 60, 62; 80, 82 are adapted to be supplied with fluid via a common fluid supply unit.

53. (New) An apparatus according to claim 52, wherein said nozzles of at least one group of nozzles 40, 44, 48; 60, 62; 80, 82 are adapted to be supplied with fluid via a common pressure line.

54. (New) An apparatus according to claim 45, wherein said nozzles of at least one group of nozzles 40, 44, 48; 60, 62; 80, 82 are adapted to be supplied with different fluids.

55. (New) An apparatus according to claim 45, wherein said nozzles of at least one group of nozzles are adapted to be activated and deactivated individually or in sub groups.

56. (New) An apparatus according to claim 45, wherein at least one of a shape of a nozzle stream, and a flow volume, of at least one nozzle of at least one group of nozzles 40, 44, 48, 60, 62, 80, 82 is adapted to be varied.

57. (New) An apparatus according to claim 45, wherein a nozzle 52 is disposed on or in the vicinity of said axis of rotation A.

58. (New) An apparatus according to claim 57, wherein said nozzle 52 is adapted to be supplied with different fluids.

59. (New) An apparatus according to claim 58, wherein at least two separate feed lines are provided for different fluids.

60. (New) An apparatus according to claim 45, wherein respectively at least one group of nozzles 40, 44, 48; 60, 62; 80, 82 is provided above and below a substrate.

61. (New) An apparatus according to claim 44, which further comprises an essentially planar carrier ring, a rotation device for rotating said carrier ring in the plane thereof about said axis of rotation A, and at least three support elements 8, which extend out of said plane of said carrier ring 5, wherein said support elements 8 form a multi-point support for a substrate 3 at a distance from said carrier ring.

62. (New) A method of treating disc-shaped substrates, including the steps of:

rotating said substrates 3 about an axis of rotation A that is disposed essentially perpendicular to a plane of said substrates;

providing at least one first group of nozzles 40, 60, 80, the nozzles of which are differently spaced relative to said axis of rotation A;

applying a first fluid to said substrates via said at least one first group of nozzles; and

controlling said nozzles of said first group individually or in sub groups to achieve a selective treatment of surface regions of a substrate 3.

63. (New) A method according to claim 62, wherein to terminate treatment with said first fluid, at least one further fluid is conducted onto said substrate 3 via at least one nozzle.

64. (New) A method according to claim 63, wherein said further fluid is conducted onto said substrate via at least one nozzle of a further group of nozzles.

65. (New) A method according to claim 63, wherein said further fluid is applied by a nozzle that is disposed closer to said axis of rotation than is a nozzle via which said first fluid is applied to said substrate in order to displace said first fluid outwardly.

66. (New) A method according to claim 63, wherein nozzles that apply said first fluid are deactivated sequentially in a direction away from said axis of rotation, or are switched over to an application of said second fluid.

67. (New) A method according to claim 64, wherein nozzles that apply said further

fluid are activated sequentially in a direction away from said axis of rotation.

68. (New) A method according to claim 63, wherein said further fluid is initially applied to said substrate in a vicinity of said axis of rotation.

69. (New) A method according to claim 63, wherein treatment with said further fluid is terminated by applying a yet further fluid in the same manner as is the treatment with said first fluid.

70. (New) A method according to claim 62, wherein said first fluid is a treatment liquid, a cleaning liquid, or a rinsing liquid.

71. (New) A method according to claim 63, wherein said one further fluid is a rinsing liquid.

72. (New) A method according to claim 63, wherein at least one further fluid is a fluid that reduces a surface tension of fluid found on said substrate.

73. (New) A method according to claim 62, wherein an upper side and a lower side of said substrate are simultaneously treated.

74. (New) An apparatus for treating disc-shaped substrates, comprising:

an essentially planar carrier ring 5;

a rotation device 10 for rotating said carrier ring 5 in the plane thereof about an axis of rotation; and

at least three support elements 8, which extend out of said plane of said carrier ring 5, wherein said support elements 8 form a multi-point support for a substrate 3 at a distance from said plane of said carrier ring 5.

75. (New) An apparatus according to claim 74, wherein said support elements 8 are provided with support surfaces that are disposed along a peripheral contour of said substrate 3.

76. (New) An apparatus according to claim 74, wherein said support elements 8 extend into a region of a central opening 6 of said carrier ring 5.

77. (New) An apparatus according to claim 74, wherein said support elements 8 extend from an inner periphery of said carrier ring 5.

78. (New) An apparatus according to claim 74, wherein said support elements 8 extend at an incline relative to said plane of said carrier ring 5.

79. (New) An apparatus according to claim 74, wherein support surfaces 12 of said support elements 8 are inclined relative to said plane of said carrier ring 5.

80. (New) An apparatus according to claim 74, wherein at least two stop surfaces 20 are provided that extend essentially perpendicular to said plane of said carrier ring 5 and that serve for limiting a lateral movement of said substrate 3.

81. (New) An apparatus according to claim 80, wherein said stop surfaces 20 are formed on said support elements 8.

82. (New) An apparatus according to claim 80, wherein said stop surfaces are provided on stop elements 27 that are separate from said support elements 8.

83. (New) An apparatus according to claim 82, wherein said stop elements 27 are movably disposed on said carrier ring 5 and are movable between a free position and a position where they contact said substrate 3.

84. (New) An apparatus according to claim 82, wherein said stop elements 27 are movable into contact with said substrate 3 by means of a rotational movement of said carrier ring 5.

85. (New) An apparatus according to claim 80, wherein said stop elements 27 have a cross-sectional configuration that widens in an essentially V-shaped manner in a direction away from said stop surfaces.

86. (New) An apparatus according to claim 74, wherein said carrier ring 5, and said rotation device that is associated therewith, are disposed below support surfaces of said support elements 8.